

Fig. 1

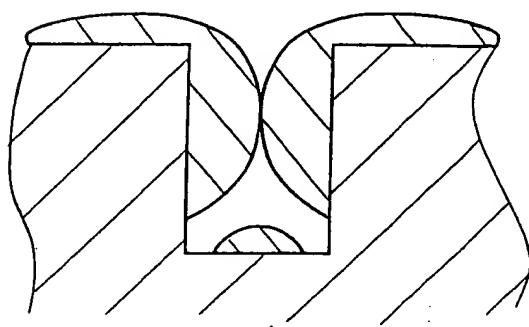


Fig. 2A

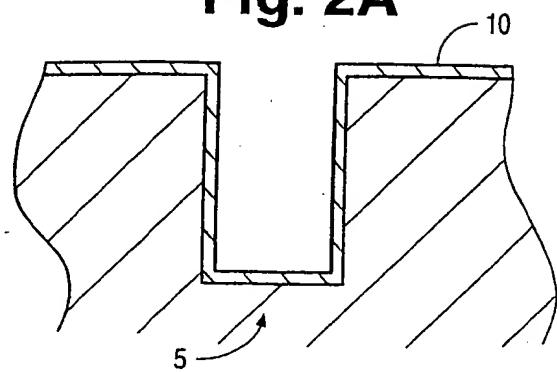


Fig. 2B

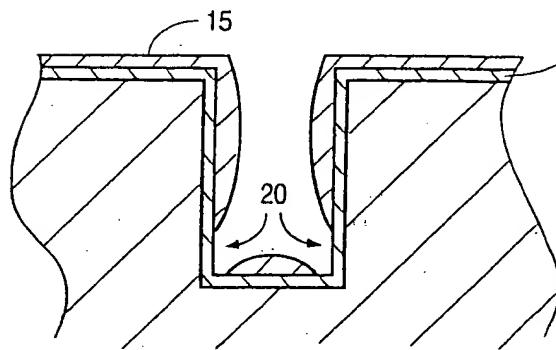


Fig. 2C

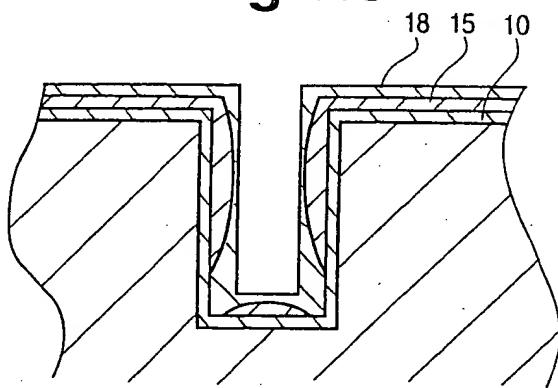


Fig. 2D

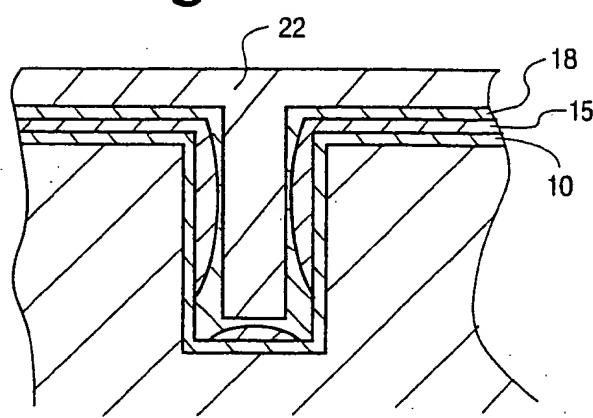
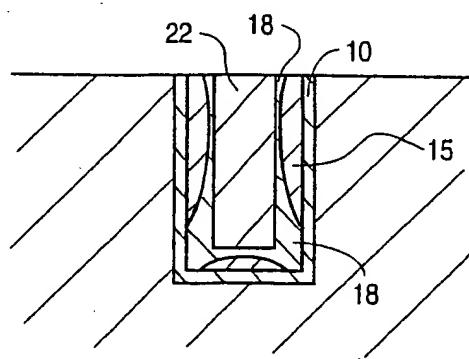


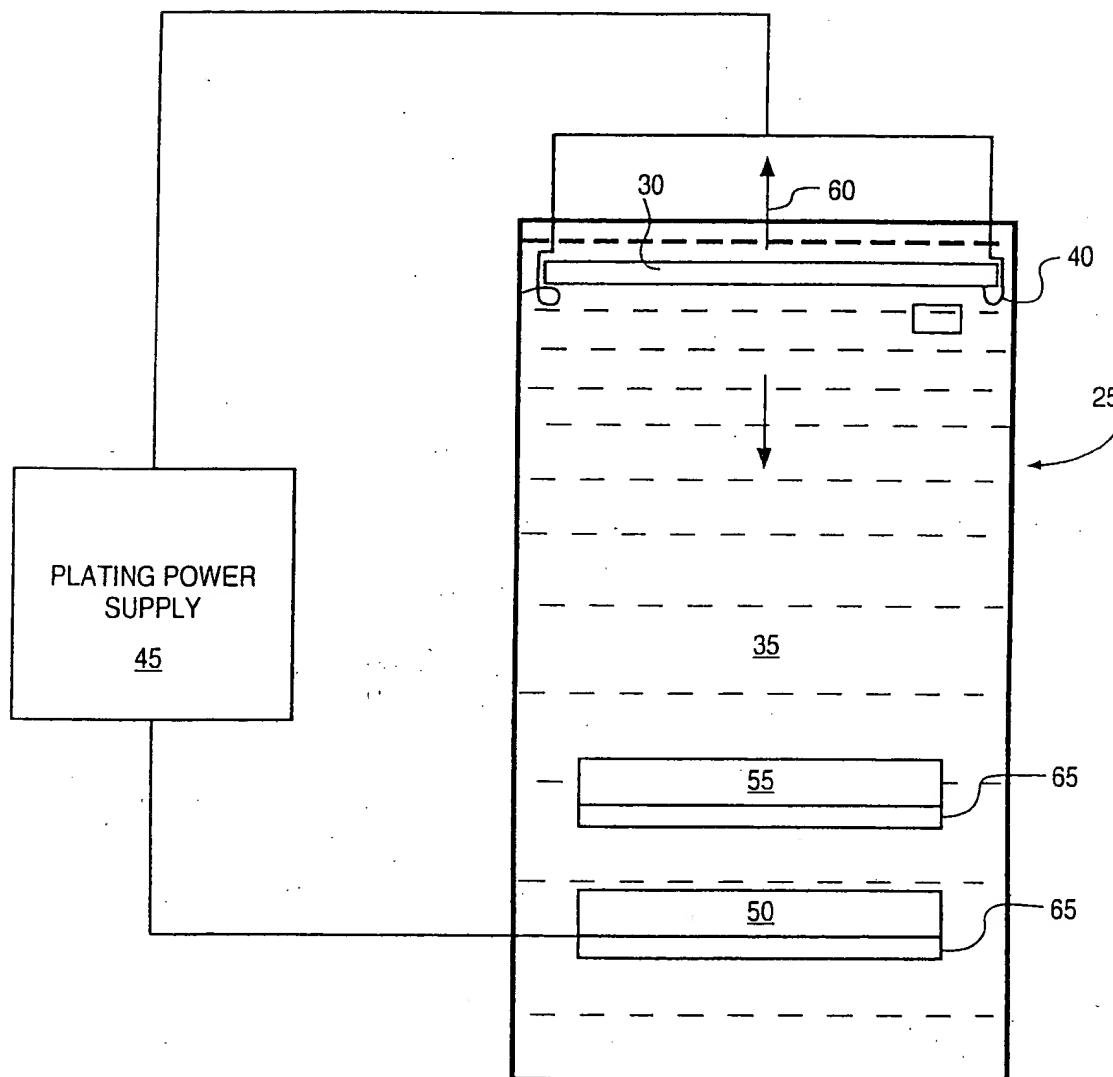
Fig. 2E



Title: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER
SEMICONDUCTOR WORKPIECE
Inventor: L. Chen
Docket No.: SEMT117581

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Fig. 3



Title: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER ON A
SEMICONDUCTOR WORKPIECE

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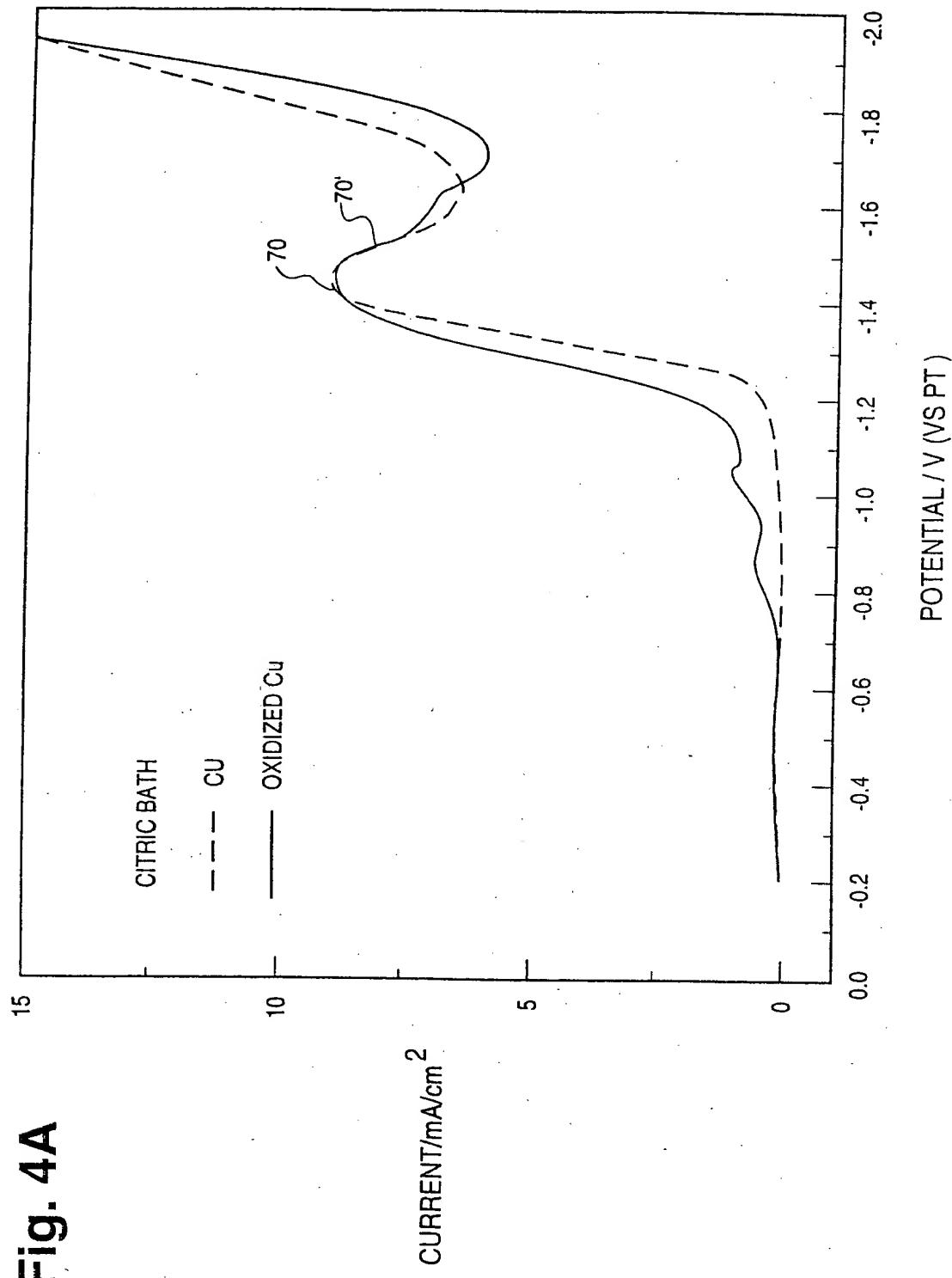
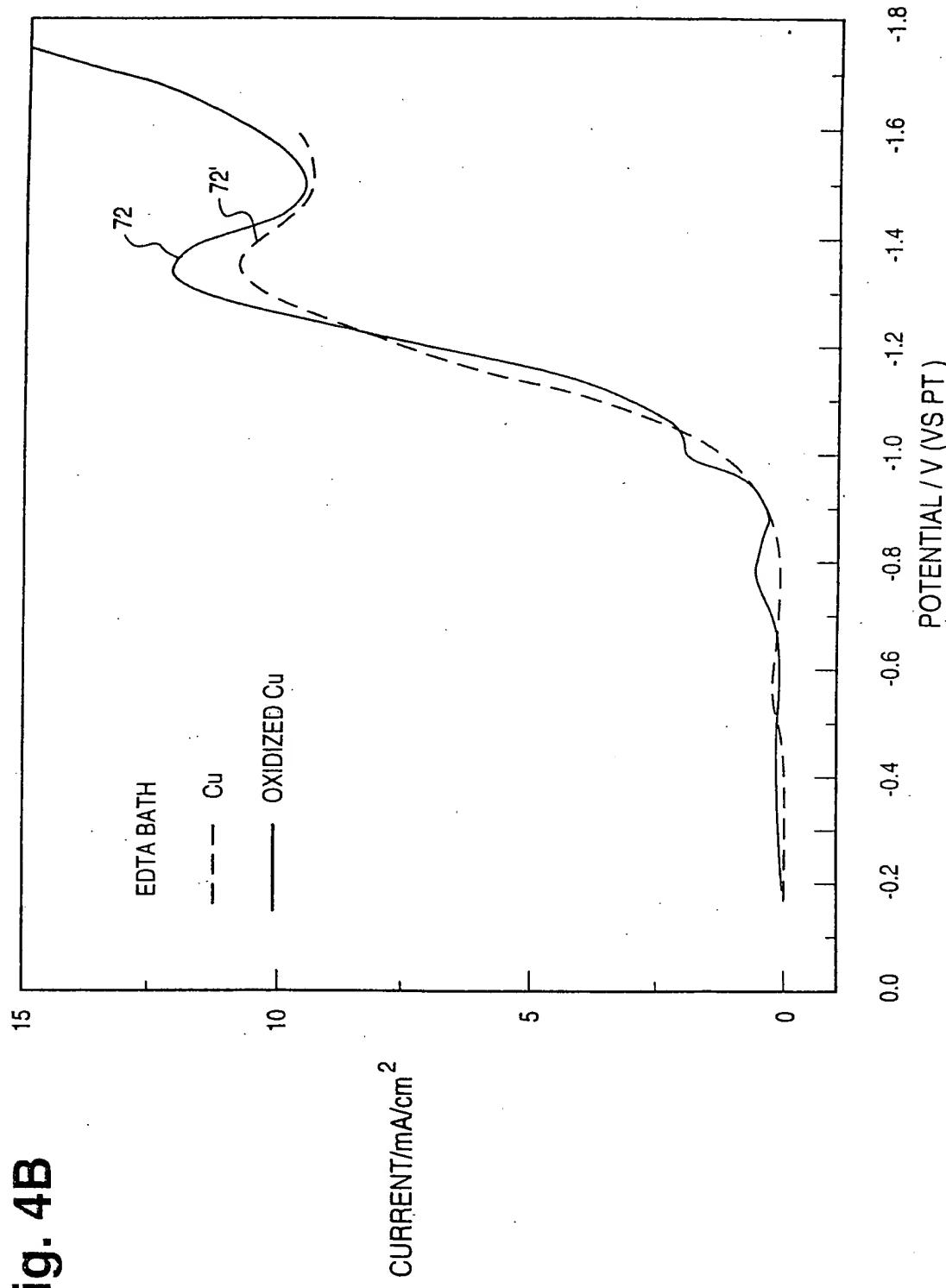


Fig. 4A

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Title: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER
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Inventor: L. Chen
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SHEET RESISTANCE CHANGE WITH ANNEALING TEMPERATURE
FOR THE DEPOSITS WITH AND WITHOUT $(\text{NH}_4)_2\text{SO}_4$

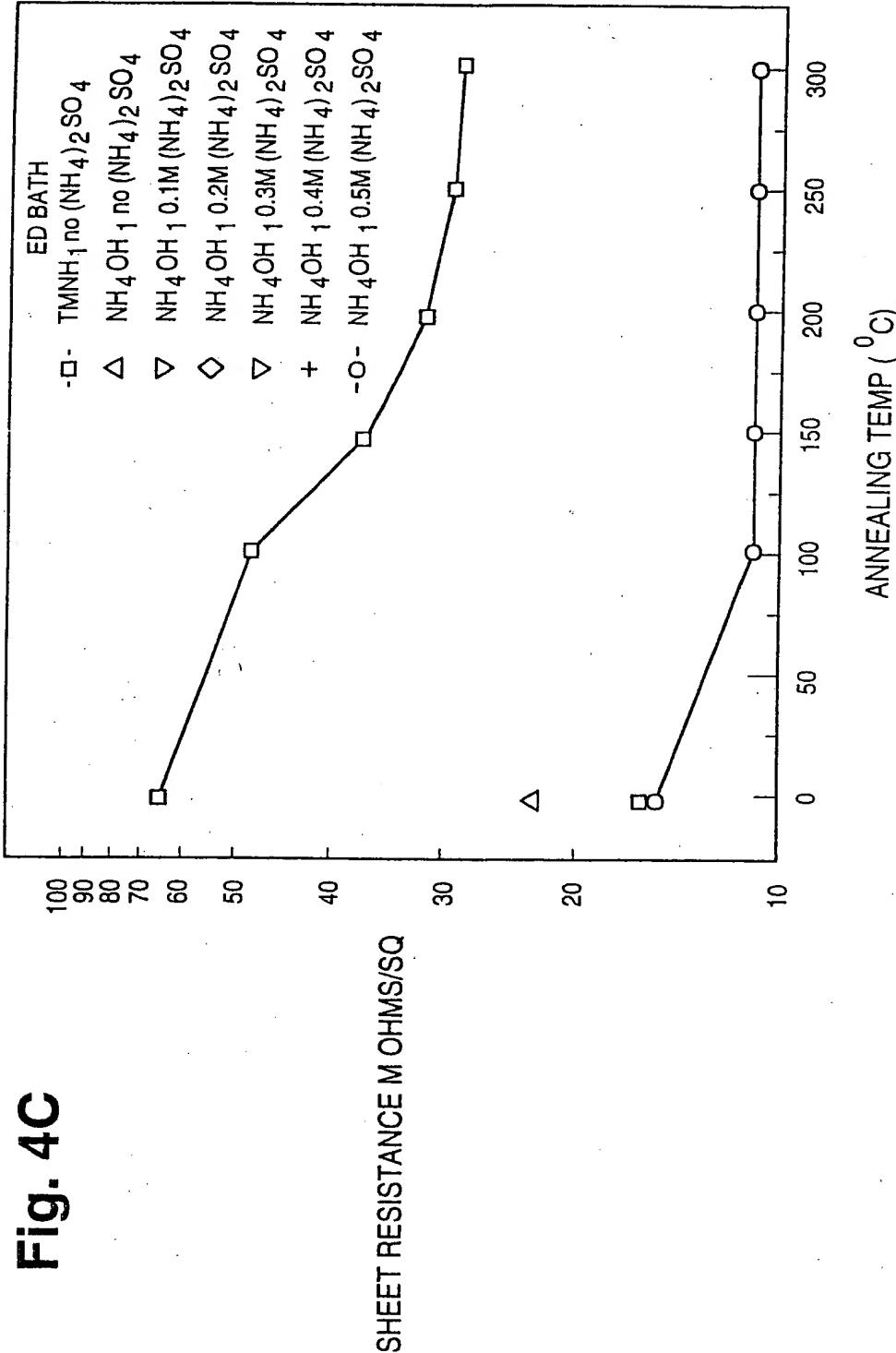


Fig. 4C

Title: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER ON
SEMICONDUCTOR WORKPIECE

Inventor: L. Chen
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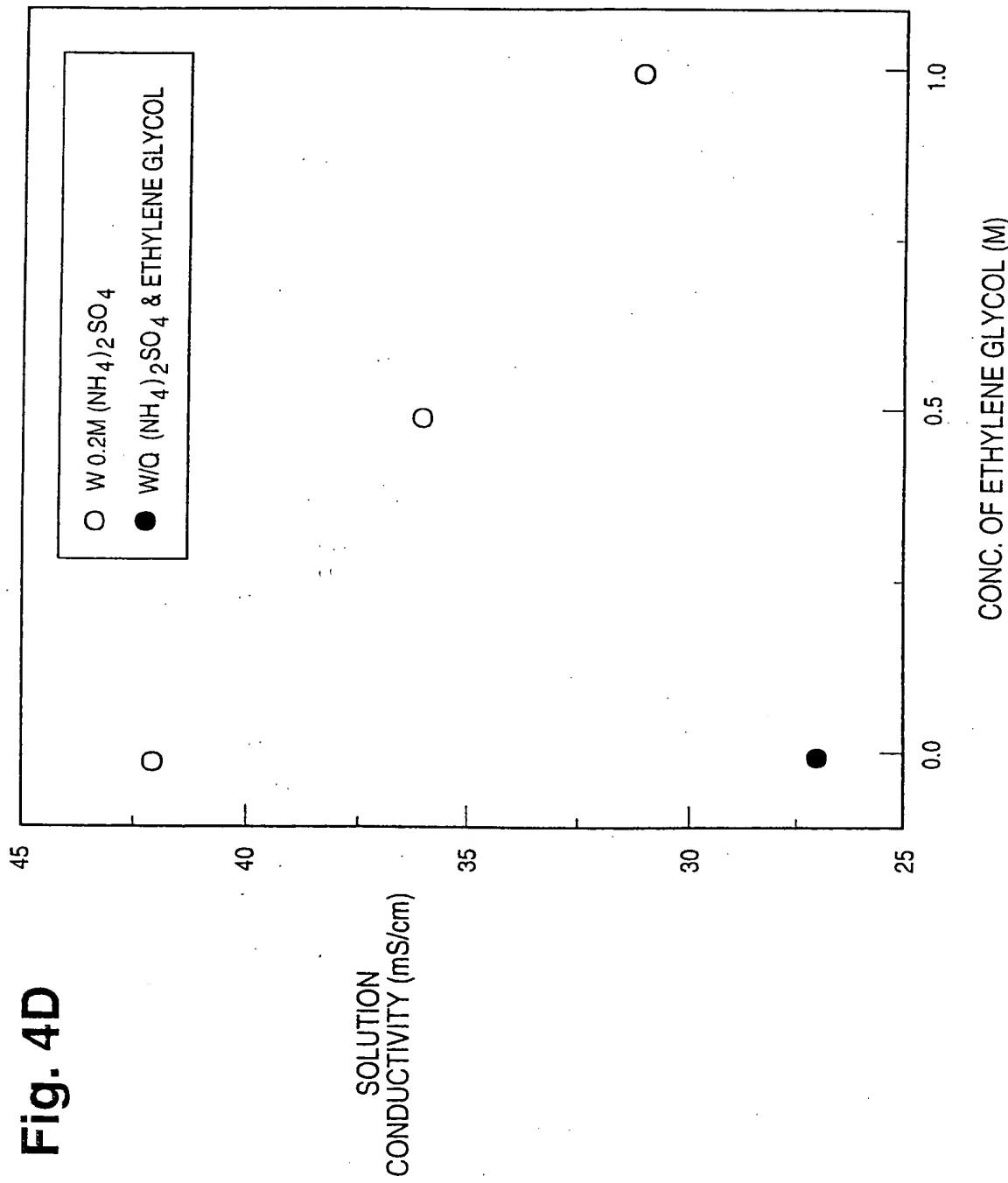


Fig. 4D

Title: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER ON
SEMICONDUCTOR WORKPIECE

Inventor: L. Chen
Docket No.: SEMT117581

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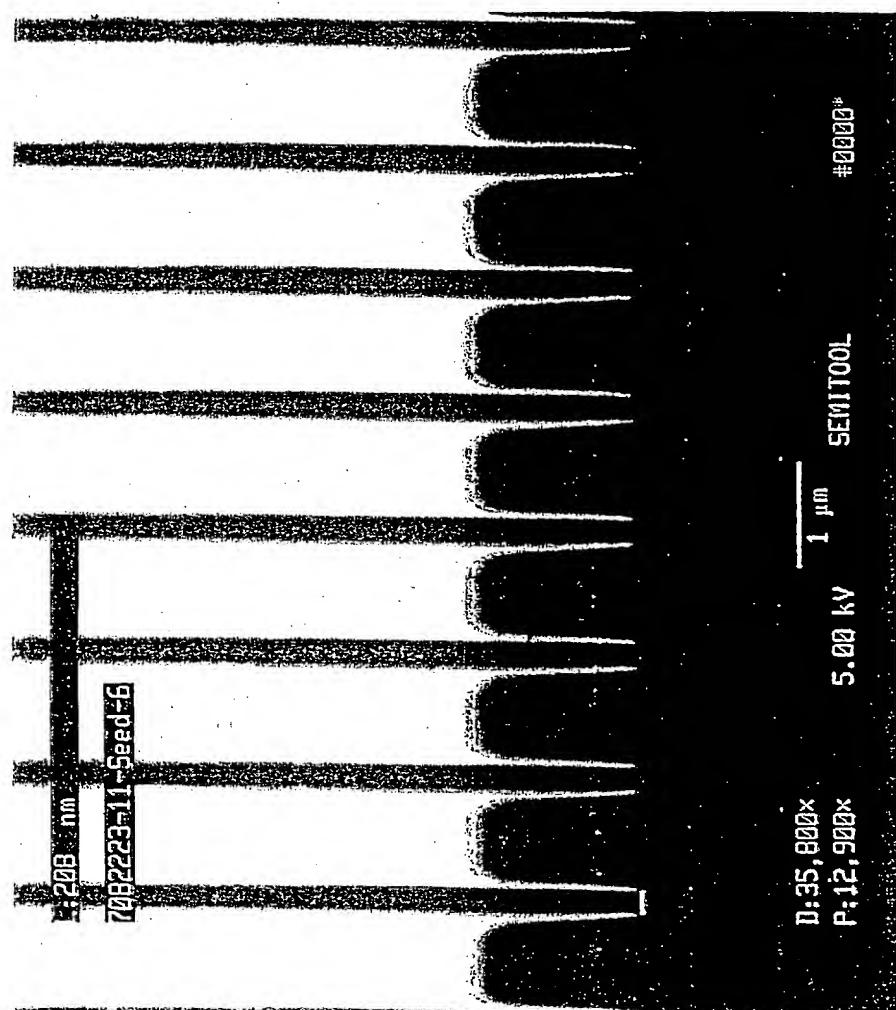


Fig. 5

APPARATUS AND METHOD FOR
COTROLYTICALLY DEPOSITING COPPER ON A
SEMICONDUCTOR WORKPIECE

Inventor: L. Chen
Docket No.: SEMT117581

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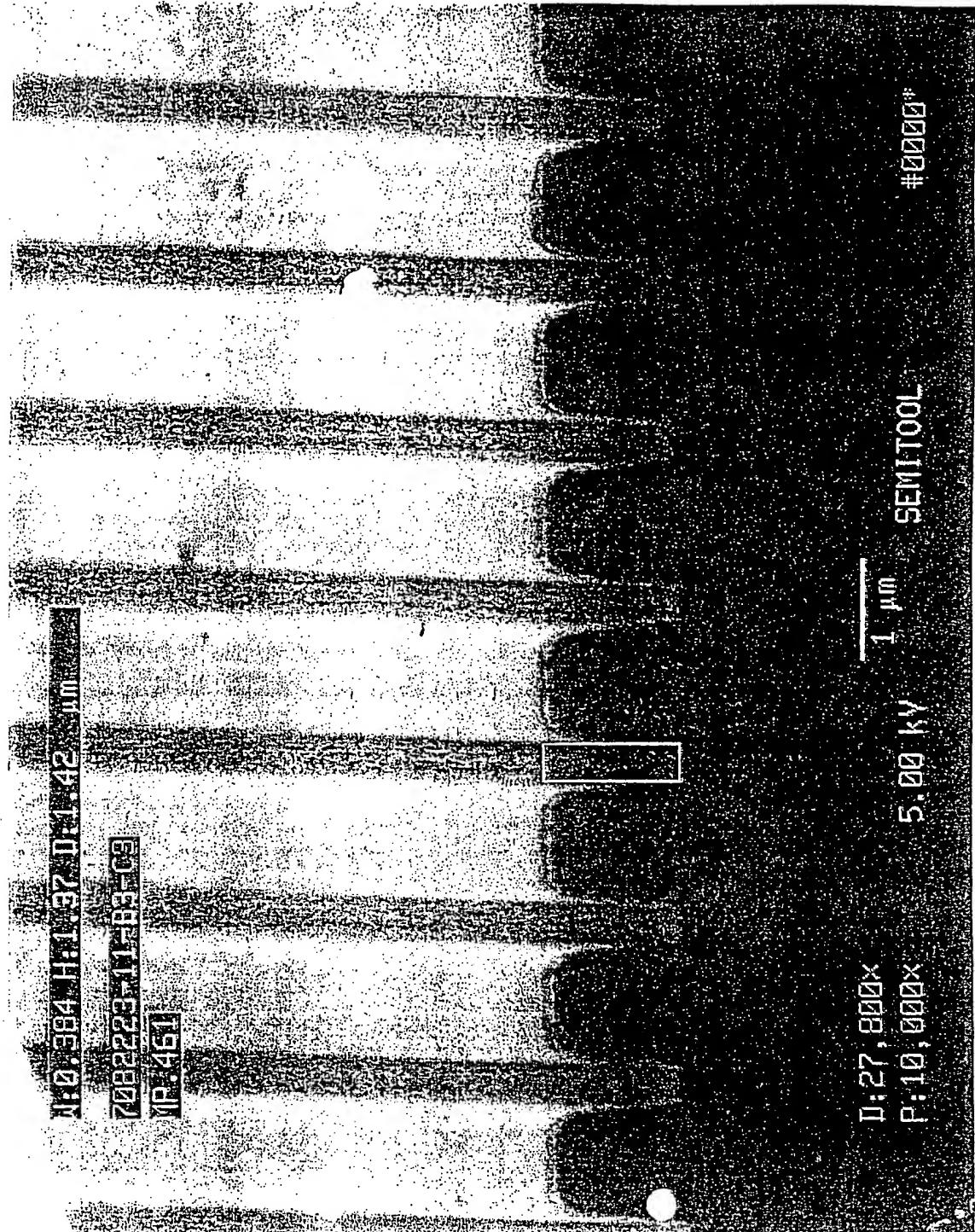


Fig. 6A

APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER ON A
SEMICONDUCTOR WORKPIECE

Inventor: L. Chen
Docket No.: SEMT117581

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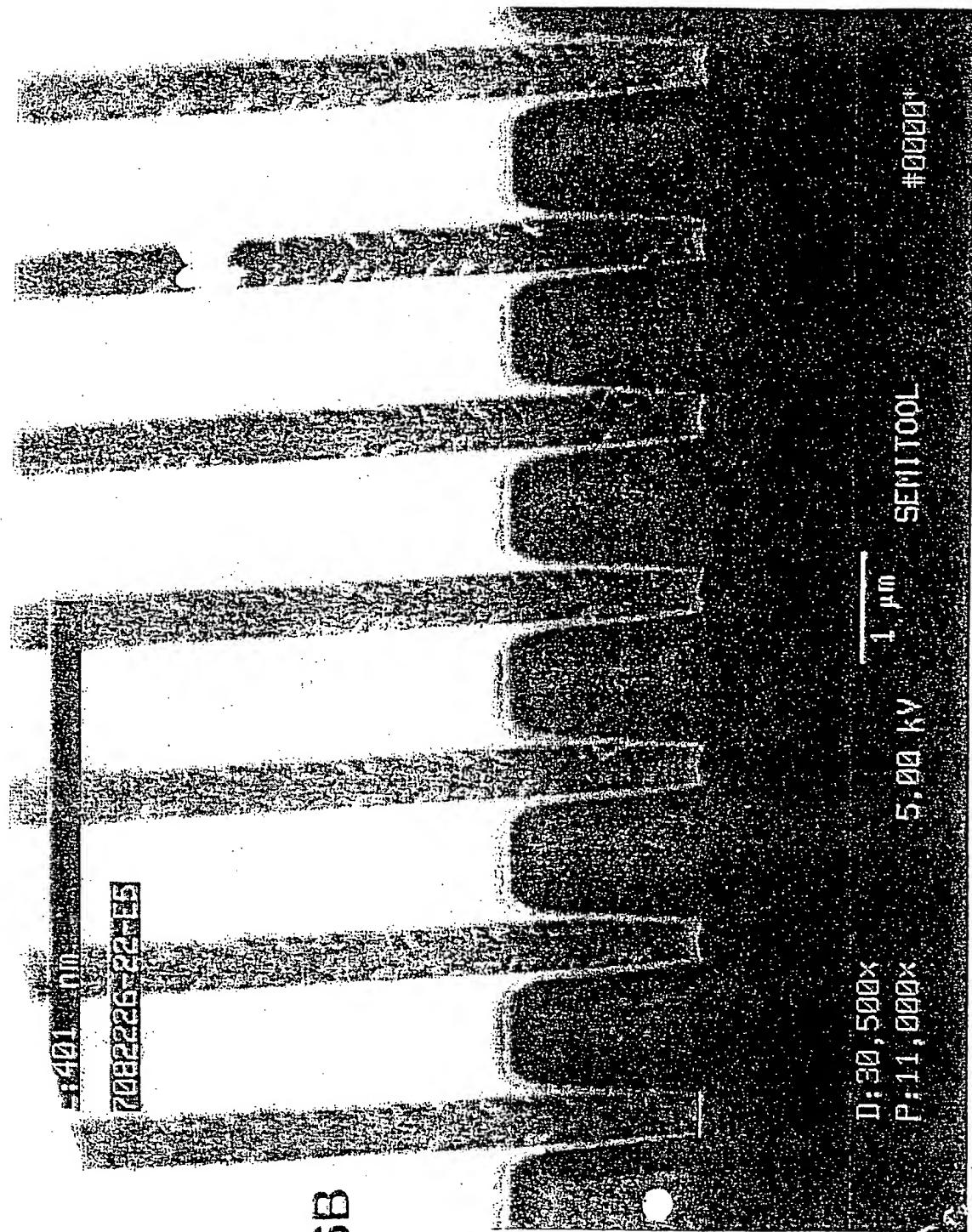


Fig. 6B

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APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING COPPER ON A
SEMICONDUCTOR WORKPIECE
Inventor: L. Chen
Docket No.: SEMT117581

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Fig. 7

